

Title (en)

FLUID EJECTION DEVICE, METHOD OF FORMING FLUID EJECTION DEVICE AND FLUID EJECTION SYSTEM

Title (de)

FLÜSSIGKEITSAUSSTOSSVORRICHTUNG, VERFAHREN ZUR HERSTELLUNG EINER FLÜSSIGKEITSAUSSTOSSVORRICHTUNG UND FLÜSSIGKEITSAUSSTOSSSYSTEM

Title (fr)

DISPOSITIF D'ÉJECTION DE FLUIDE, PROCÉDÉ DE FORMATION D'UN DISPOSITIF D'ÉJECTION DE FLUIDE ET SYSTÈME D'ÉJECTION DE FLUIDE

Publication

EP 3277430 A4 20181114 (EN)

Application

EP 16771755 A 20160325

Priority

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Abstract (en)

[origin: WO2016157867A1] A fluid ejection device (100) includes a body (102) defining an interior bore (108), a fluid reservoir (110), and a fluid ejection chip (130). The fluid reservoir (110) defines an interior passage (185) that receives a fluid, the interior passage(185) in fluid communication with the interior bore (108) of the body (102). The fluid ejection chip (130) is coupled with the body (102) and includes one or more fluid ejection actuators. The fluid ejection chip (130) has one or more interior fluid paths in fluid communication with the interior bore (108) of the body (102) so that the fluid ejection chip (130) ejects the fluid upon activation of the one or more fluid ejection actuators.

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

- [XYI] US 2008309740 A1 20081218 - ALDRICH CHARLES STANLEY [US]
- [XY] US 2011181672 A1 20110728 - WAGNER WILLIAM R [US], et al
- [XI] US 2007268347 A1 20071122 - AMANO KAZUHIKO [JP], et al
- [XI] US 2006227173 A1 20061012 - BUCHANAN JEFFERY J [US], et al
- [XI] JP 2012086370 A 20120510 - SEIKO EPSON CORP
- [X] US 2005157129 A1 20050721 - MERZ ERIC A [US], et al
- [X] US 2013070021 A1 20130321 - NISHIMURA HIDEAKI [JP], et al
- [Y] US 2010282342 A1 20101111 - AOYAMA KAZUHIRO [JP], et al
- [Y] EP 1870243 A1 20071226 - SAMSUNG ELECTRONICS CO LTD [KR]
- [A] US 2005012791 A1 20050120 - ANDERSON FRANK E [US], et al
- [A] US 2010238239 A1 20100923 - SHINKAI KATSUMI [JP]
- See references of WO 2016157867A1

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